



January 21, 2022  
Revised: February 7, 2022  
Doc.# PC#21H045+

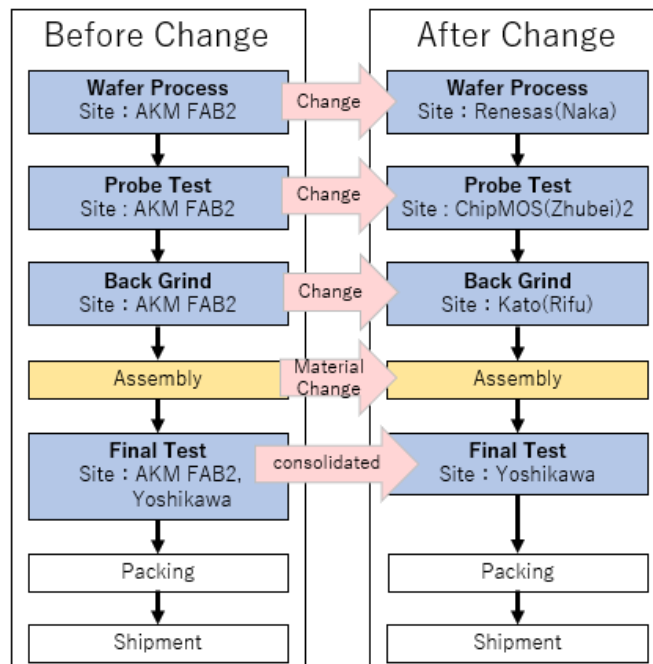
### Product / Process Change Notice

The fire in FAB2(Nobeoka Plant) that occurred on October 20, 2020 caused significant damage to the facility. Therefore, AKM is hereby announcing the change of the site as below. **In addition, we changed the die bond material (Ag paste) from the lot after the start of alternative production.** This is a change approval request which describes the change details and products affected.

#### ◆ Affected Product

AKM Part No	Your Company's Part No
AK4558EN	

#### ◆ Change details



#### ◆ Site: Before Change

AKM FAB2: AKM Nobeoka Factory  
5-4960 Nakagawara-cho, Nobeoka-shi, Miyazaki, Japan

#### ◆ Site: After Change

##### < Wafer Process >

Renesas(Naka): Renesas Electronics Corporation Naka Fab  
751, Horiguchi, Hitachinaka-shi, Ibaraki, Japan

##### < Probe Test >

ChipMOS(Zhubei)2: CHIPMOS TECHNOLOGIES INC. Zhubei Fab. II.  
No.112, Zhonghe Street, Zhubei City, Hshinchu County, Taiwan, R.O.C.

##### < Back Grind >

Kato(Rifu): KATO Electric Co.,Ltd Rifu Fab  
6-11-1, Shirakashidai, Rifu-cho, Miyagi-gun, Miyagi 981-0134, Japan

< Final Test >

Yoshikawa) Yoshikawakogyo RF Semicon Co.,Ltd. Shintomi Fab  
4637-1, Kamitonda, Shintomi-cho, Koyu-gun, Miyazaki, Japan

◆ Die bond material change

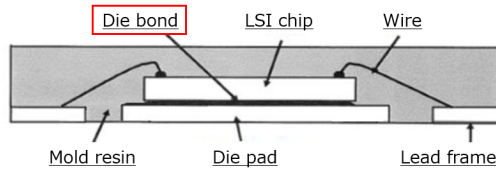
Reason : EOL of the die bond material

Change point : Only the model number used for the die bond material is changed.

\*Die bond material supplier is "NOT" changed.

\*The type of Ag paste is "NOT" changed.

\*New die bond material is used in many of our products.



◆ Proposed First ship date  
August 2022

If you agree to the foregoing conditions, please indicate your acknowledgement and acceptance by putting the signature of your authorized representative in the space provided below and return one original to us.

Sincerely yours,

*N. Kurita*

Naoyuki Kurita  
Vice President

Accepted and Agreed by:

\_\_\_\_\_  
Name:  
Title:  
Date: